SF202C 高耐热聚酰亚胺薄膜覆盖膜

SF202C High solder resistance polyimide film based coverlay

特点

- 优异的耐离子迁移特性。
- 优异的耐热老化性。
- 阻燃性达到UL94 VTM-0级。
- 高频下较低的介电常数、介质损耗角正切。
- 溢胶量低,加工性好,适于快速压合和传统压合。
- 满足RoHS指令要求,不含铅、汞、镉、六价铬、 多溴联苯、多溴联苯醚等。

FEATURES

- Excellent anti-ion-migration performance.
- Excellent thermal aging resistance
- Flammability UL94 VTM-0.
- Low Dk & Low Df at high frequency
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb,Hg, Cd, Cr⁶⁺,PBB,PBDE, etc..

应用领域

汽车等对安全性、可靠性,要求较高的电子产品。

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APPLICATIONS

For security, high reliability requirements of electronic products.

性能表 GENERAL PROPERTIES

性能项目 Test Item		试验处理条件	单位 Unit	性能数据 Property Data		
		Treatment		IPC 标准值 [*]	典型值 Typical Value	
		Condition		Standard	SF202C 0515	SF202C 1025
溢胶量					<0.15	<0.15
Resin Flow		A	mm	-	<0.15	<0.15
剥离强度 ¹		A		≥0.8	0.8	1.0
Peel Strength (90°) ¹		288℃,5s	N/mm	≥0.8	0.8	1.1
热应力 ¹		200*0 20-			无分层、无起泡	无分层、无起泡
Thermal Stress ¹		288℃,20s	-	-	No delamination	No delamination
尺寸稳定性	MD	撕纸后	%	±0.2	±0.15	±0.15
Dimensional Stability	TD	After peeling off the paper	%	±0.2	±0.15	±0.15
介电常数(1MHz)		C-24/23/50		≪4.0	3.2	3.2
Dielectric Constant(1MHz)		C-24/23/30	-	≪4.0	J.Z	5.2
介质损耗角正切(1MHz)		C-24/23/50		≤0.04	0.008	0.008
Dissipation Factor (1MHz)		-	≪0.04	0.008	0.008	
燃烧性 C-48/23/50			UL94 V-0	UL94 V-0	UL94 V-0	
Flammability		0-40/23/30		0134 0-0	0134 1-0	0194 0-0

注释 Explanations: C = Humidity conditioning;

- E = 恒温处理条件 Temperature conditioning.
- 1. 与铜箔光面压合再固化后测试。Testing after laminating with shining side of copper foil in suitable condition.
- * Certified to IPC-4203/21 Poyimide dielectric with polyimide adhesive

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产品规格代码描述 Product Code Description

SF202C 10 25



胶粘剂厚度 Adhesive Thickness: 13 - 13 μ m; 25 - 25 μ m

PI 膜厚度 PI film Thickness: 10 - 25 µ m

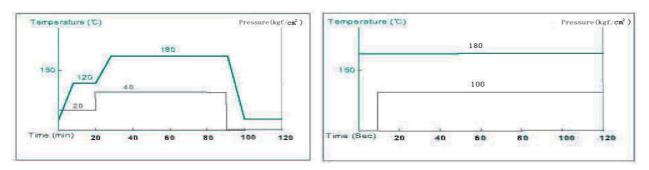
生益覆盖膜产品编号 Shengyi Coverlay Designation

<u>常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS</u>

产品规格 Specifications	PI 膜厚度(μm) PI film Thickness (μ m)	胶粘剂厚度(μm) Adhesive Thickness (μm)	应用领域 Applications
SF202C 0515	12.5	15	
SF202C 0520	12.5	20	汽车电子等
SF202C 0525	12.5	25	automotive
SF202C 1025	25	25	electronics etc.
SF202C 1030	25	30	

压板推荐 PRESS PROPOSE HOT PRESSING CYCLE

FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整;采用快压方式,后固化条件是 160-180℃、60-90 分钟。 The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-180℃ for 60-90min.

包装 PURCHASING INFORMATION

产品宽度250+2/-0mm或500+2/-0mm,每卷100+2/-0米或200+2/-0米;其它规格、尺寸可根据客户要求而定。 SF202C is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

储存条件 STORAGE CONDITION

贮存在干燥的室内;以原始包装贮存在4-10 ℃的冷藏室里,贮存期为三个月。 Stored in the room of dryness . Three months when stored in the original packaging at 4-10 ℃.